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Multi-Channel
Silicon ESD Protector
Overvoltage Protection Device

PRODUCT: SESD1004Q4UG-0020-090

DOCUMENT: SCD28190
REV LETTER: C
REV DATE: March 2, 2012
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Specification Status: RELEASED

BENEFITS

- Industry-leading lowest capacitance; provides lowest insertion loss for high speed data signals
- Industry's smallest footprint and lowest profile multi-channel ESD array helps to optimize board space
- Flow-through and single connection design helps routing PCB matched impedance high speed data lines
- Helps protect electronic circuits against damage from Electrostatic Discharge (ESD), surge and cable discharge events
- Assists equipment to pass IEC61000-4-2, level 4 testing

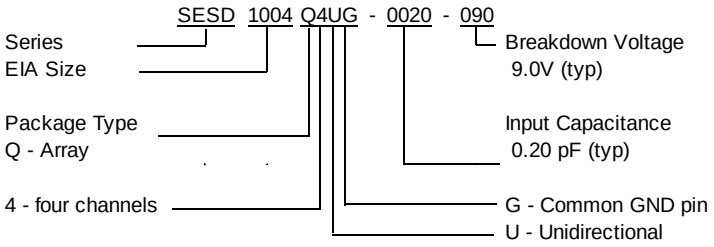
FEATURES

- Low capacitance: 0.20 pF (200fF) (typ)
- Low leakage current: 25nA @ 5V (typ)
- Low clamping voltage: +9.20 / -0.8V (typ) @ (tp=8x20µs, Ipp=2A)
- ESD maximum rating per IEC61000-4-2 standard:
  - 20kV contact discharge
  - 20kV air discharge
- Surge: 2A (max) @ (tp=8x20µs) per IEC61000-4-5
- Small size and low profile: XDFN array packages 0.31mm height

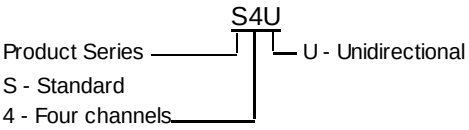
APPLICATIONS

- Consumer, mobile and portable electronics
- Tablet PC and external storage with high speed interfaces
- Ultra-high speed data lines
- USB 3.0/2.0, HDMI 1.3/1.4, DisplayPort, Thunderbolt (Light Peak), V-by-One HS, and LVDS interfaces
- Applications requiring high ESD performance in small DFN packages

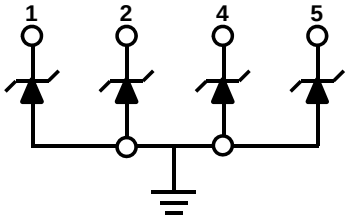
PART NUMBERING



PART MARKING



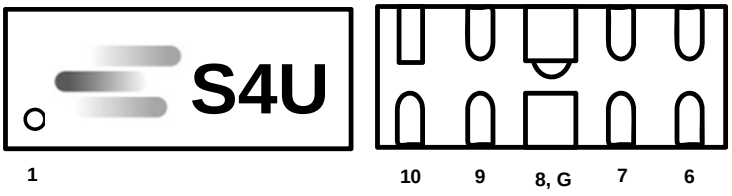
SCHEMATIC AND PIN CONFIGURATION



MATERIALS INFORMATION

RoHS Compliant — Directive 2000/53/EC Compliant
ELV Compliant — Directive 2002/95/EC Compliant
Halogen Free * — HF
Lead Free — Pb

* Halogen Free refers to: Br≤900ppm, Cl≤900ppm, Br+Cl≤1500ppm
SESD devices meet MSL-1 Requirements
DFN case epoxy meets UL 94 V-0



Top View

Bottom View

DEVICE MAXIMUM RATING

ESD Withstand[1] (IEC 61000-4-2, level 4)		Temperature		Peak Current (tp=8x20µs)
Contact (kV)	Air (kV)	Operating (^{o}C)	Storage (^{o}C)	Ipp (A)
20	20	-55 to +125	-55 to +150	2.0

[1] 20kV @ 1 pulse; 10kV @ 100 pulses; 8kV @ 1,000 pulses (under IEC6100-4-2)

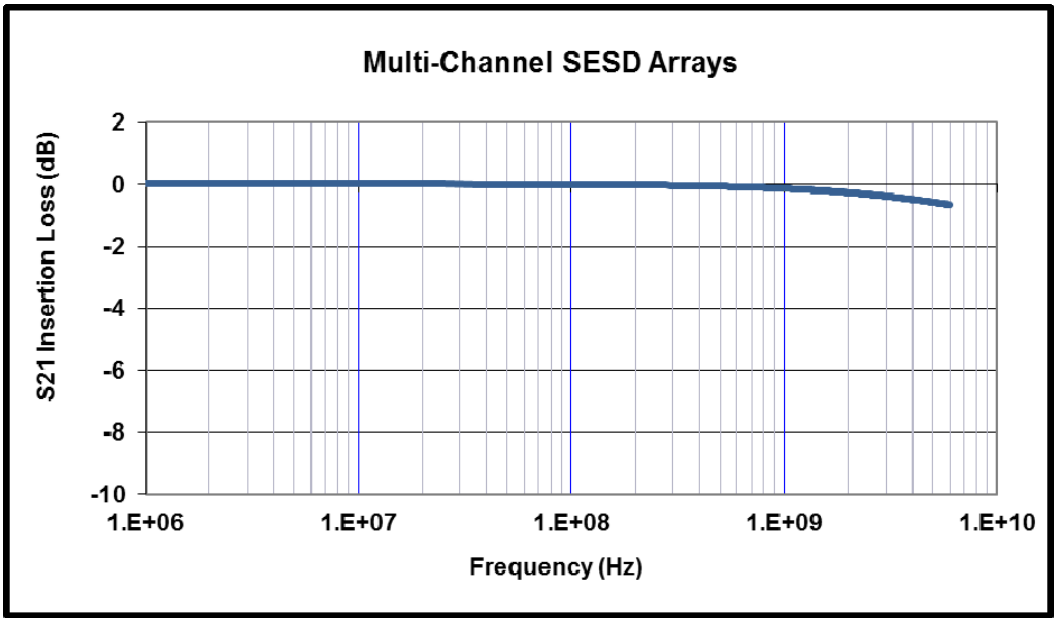
- Device maximum rating @ T = 25ºC, unless otherwise specified
- Caution: Stress exceeding Device Maximum Ratings may damage the device
  Prolonged exposure to stresses above the Recommended Operating Conditions may affect device reliability

DEVICE ELECTRICAL CHARACTERISTICS

Input Capacitance @ V_R = 0V, f = 3GHz, I/O to GND (pF)		Breakdown Voltage V_{BR} @ I_T=1mA (V)	Reverse Working Voltage (V)		Reverse Leakage Current I_L @ V_{RWM}=5.0V (nA)		Clamping Voltage V_{CL} @ Ipp=2.0A (V)
Typ	Maximum	Typ	Min	Max	Typ	Max	Typ
0.20	0.22	+9.00 / -0.80	0	+8.00	25.0	50.0	+9.20 / -0.80

- All device electrical characteristics @ T = 25ºC, unless otherwise specified

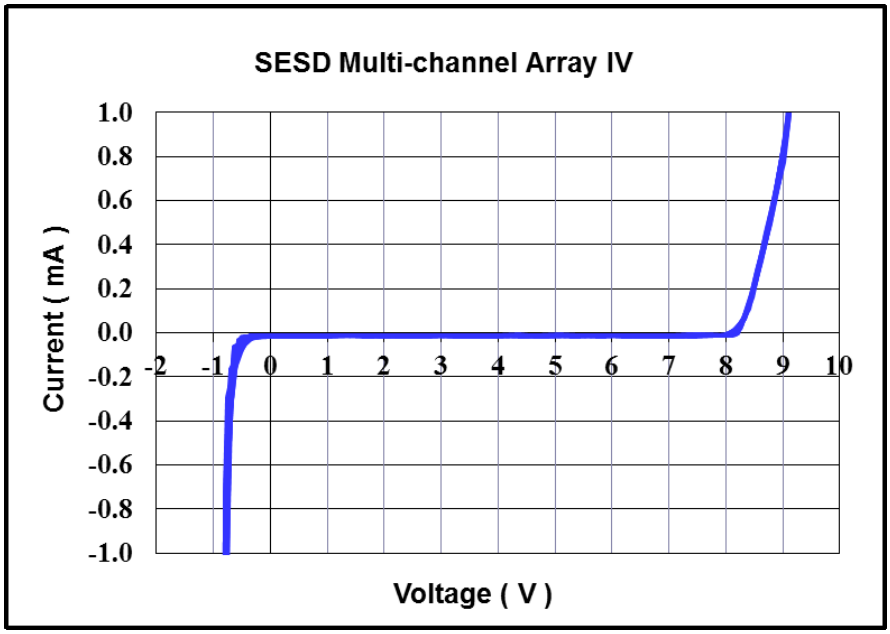
FIGURE 1. INSERTION LOSS DIAGRAM



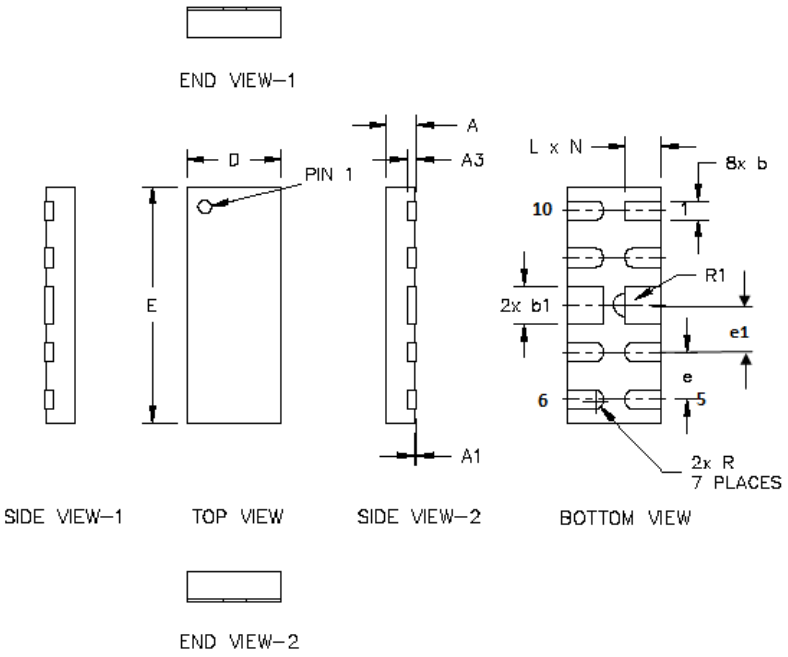
Application	Bit Rate (Gbps)	@Freq (GHz)	Ins. Loss (dB)
HDMI 1.4 (1080P)	2.25	1.13	-0.15
DisplayPort	2.70	1.35	-0.20
HDMI 1.4 (4K / QuadHD)*	3.40	1.70	-0.23
USB3.0	5.00	2.50	-0.29
eSATA	6.00	3.00	-0.35
Thunderbolt	10.0	5.00	-0.50

*HDMI 4K / QuadHD resolutions (4096 x 2160) ready

FIGURE 2. DEVICE IV CURVE



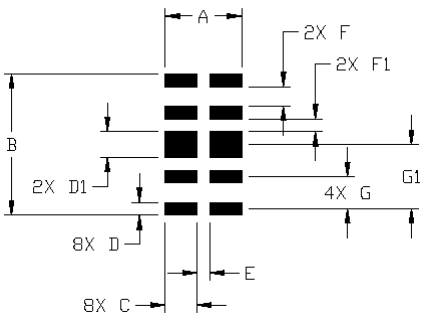
DEVICE DIMENSIONS



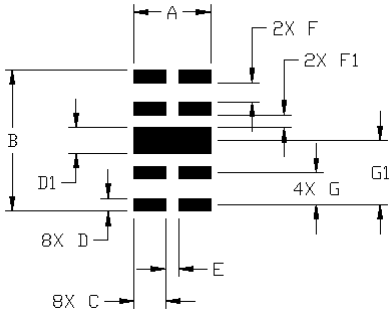
	SESD1004Q4UG-0020-090					
	Millimeters			Inches		
Dim	Min	Nom	Max	Min	Nom	Max
A	0.30	0.31	0.32	0.012	0.012	0.013
A1	0.00	--	0.05	0	--	0.002
A3	0.10 ref.			0.004 ref.		
D	0.90	1.00	1.10	0.035	0.039	0.043
E	2.40	2.50	2.60	0.094	0.098	0.102
b	0.15	0.20	0.25	0.006	0.008	0.010
b1	0.35	0.40	0.45	0.014	0.016	0.018
L	0.30	0.38	0.43	0.012	0.015	0.017
e	0.50 BSC			0.020 BSC		
e1	0.50 BSC			0.020 BSC		
N	10			10		
R	0.08 BSC			0.003 BSC		
R1	0.13 BSC			0.005 BSC		

BSC – Basic Spacing between Centers

RECOMMENDED LANDING PATTERN:



Recommended



Alternate

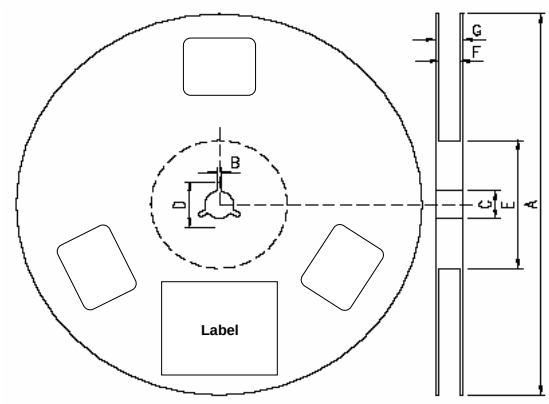
SESD Landing Pad Layout 10 Pin 4-ch Standard FT Array		
Symbol	**Millimeters**	**Inches**
A	1.20	0.047
B	2.20	0.087
C	0.50	0.020
D	0.20	0.008
D1	0.40	0.016
E	0.20	0.008
F	0.30	0.012
F1	0.20	0.008
G	0.50 BSC	0.020 BSC
G1	1.00 BSC	0.039 BSC

BSC – Basic Spacing between Centers

PACKAGING

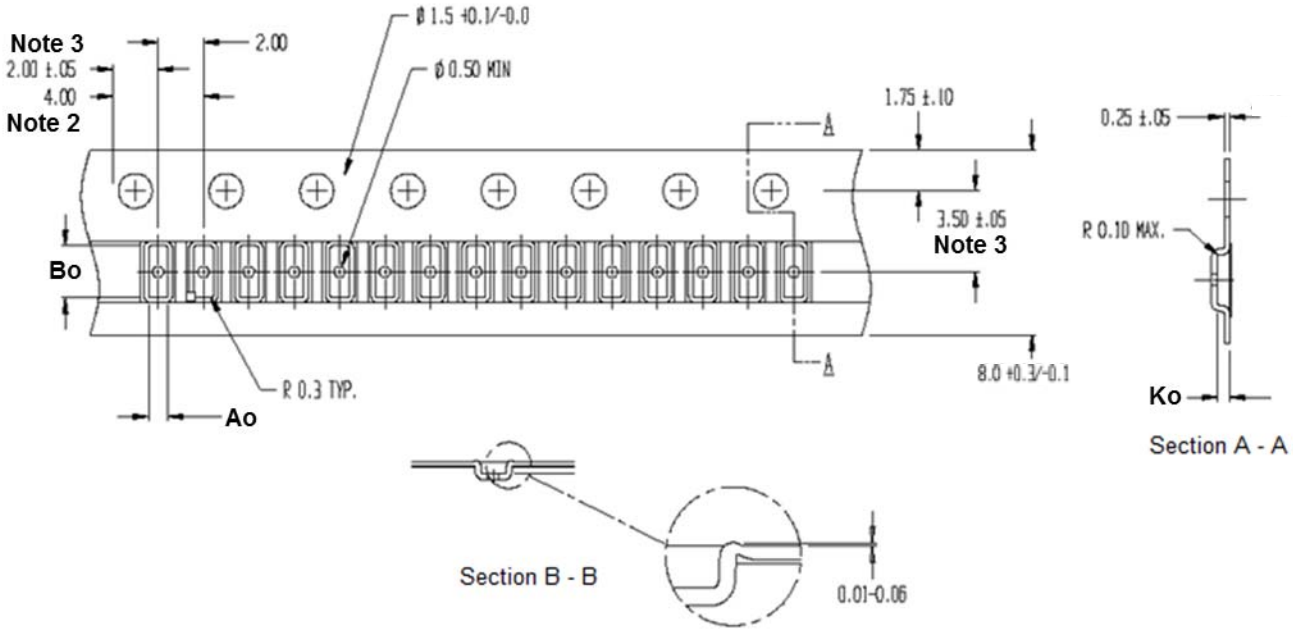
Packaging	Tape & Reel	Standard Box
SESD1004Q4UG-0020-090	5,000	25,000

REEL DIMENSIONS



Dimensions	A	B	C	D	E	F	G
(mm)	180.0 ± 1.5	2.3. 0 ± 0.2	13.0 + 0.5 / -0.2	17.3 ± 0.2	60.5 ± 1.5	8.4 +1.5/-0.0	14.4 (max)

CARRIER TAPE DIMENSIONS



Ao	1.20 ± 0.05
Bo	2.70 ± 0.05
Ko	0.51 ± 0.05

Note 1. All dimensions in mm
Note 2. 10 sprocket hole pitch cumulative tolerance ± 0.2
Note 3. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole
Note 4. Ao and Bo are calculated on a plane at a distance "R" at the bottom of the pocket
Note 5. Tolerances unless noted 1PL ± 0.20, 2PL ± 0.10

SOLDER REFLOW RECOMMENDATION

A	Temperature ramp up 1	From ambient to Preheating temperature	30s to 60s
B	Preheating	140°C - 160°C	60s to 120s
C	Temperature ramp up 2	From Preheating to Main heating temperature	20s to 40s
D	Main heating	at 200°C at 220°C at 240°C at 260°C	60s ~ 70s 50s ~ 60s 30s ~ 40s 5s ~ 10s
E	Cooling	From main heating temperature to 100°C	4°C/s (max)

FIGURE 3. REFLOW PROFILE